

Electrical Characteristics (T_J=25 C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	30			V	
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25℃ , I _D =1mA		0.025		V/°C	
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =4.5V , I _D =5A		27	32	mΩ	
		V _{GS} =2.5V , I _D =4A		39	45		
V _{GS(th)}	Gate Threshold Voltage	V V 1 050 A	0.5	0.8	1.0	V	
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$-V_{GS}=V_{DS}$, $I_D=250uA$		-4.8		mV/℃	
I _{DSS}	Drain-Source Leakage Current	V _{DS} =24V , V _{GS} =0V , T _J =25℃			1		
		V _{DS} =24V , V _{GS} =0V , T _J =55℃			5	- uA	
I _{GSS}	Gate-Source Leakage Current	V_{GS} = $\pm 20V$, V_{DS} = $0V$			±100	nA	
gfs	Forward Transconductance	V _{DS} =5V , I _D =5A		7		S	
R _g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		2.5	5	Ω	
Qg	Total Gate Charge (4.5V)			5.5	8.4	nC	
Q _{gs}	Gate-Source Charge	V _{DS} =15V , V _{GS} =4.5V , I _D =5A		2.1	3.5		
Q _{gd}	Gate-Drain Charge			1.5	2.9		
T _{d(on)}	Turn-On Delay Time	V_{DD} =15V , V_{GS} =10V , R_{G} =3.3 Ω		2.2	4.2	- ns	
T _r	Rise Time			6.8	9		
T _{d(off)}	Turn-Off Delay Time			20	40		
T _f	Fall Time			3.5	5		
C _{iss}	Input Capacitance			525	600	pF	
Coss	Output Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		57	112		
C _{rss}	Reverse Transfer Capacitance			45	91		

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I _S	Continuous Source Current ^{1,4}	\/ -\/ -0\/ Force Comment			5.6	Α
I _{SM}	Pulsed Source Current ^{2,4}	$V_G=V_D=0V$, Force Current			18	Α
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25℃			1.4	V
t _{rr}	Reverse Recovery Time			18		nS
Q _{rr}	Reverse Recovery Charge	IF=5A , dI/dt=100A/ μ s , T $_{J}$ =25 $^{\circ}$ C		1		nC

Note

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, t<10 sec.
- 2.The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%
- 3. The power dissipation is limited by 150 ℃ junction temperature
- 4. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics

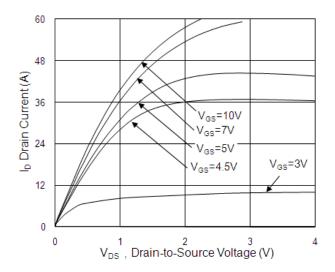


Fig.1 Typical Output Characteristics

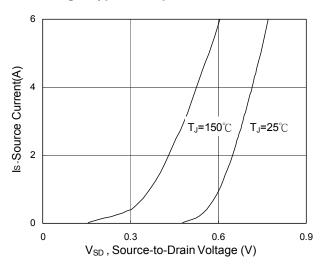


Fig.3 Forward Characteristics Of Reverse

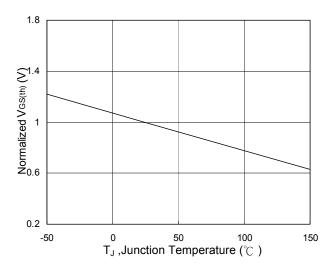


Fig.5 Normalized V_{GS(th)} vs. T_J

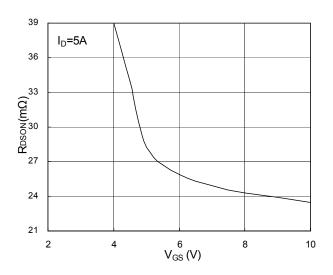


Fig.2 On-Resistance vs. Gate-Source

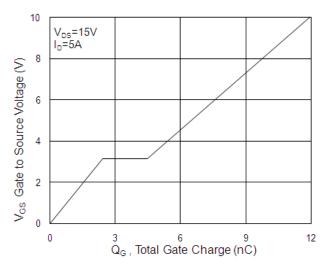


Fig.4 Gate-Charge Characteristics

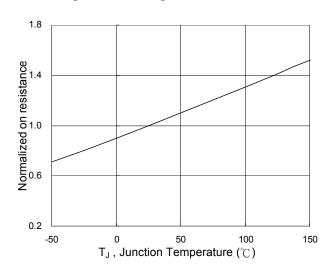
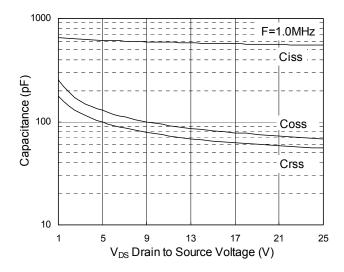


Fig.6 Normalized R_{DSON} vs. T_J





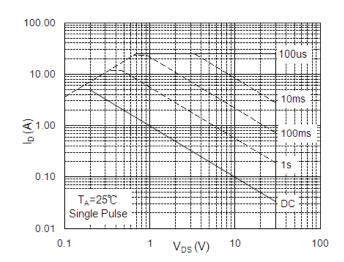


Fig.7 Capacitance

Fig.8 Safe Operating Area

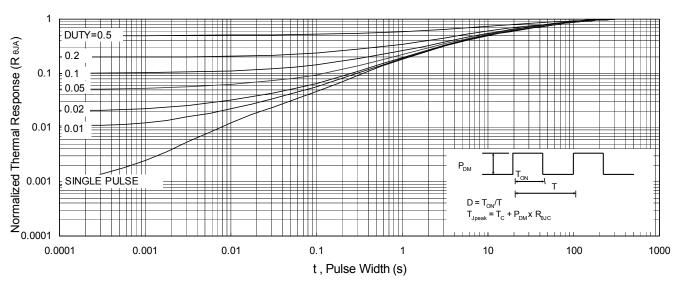


Fig.9 Normalized Maximum Transient Thermal Impedance

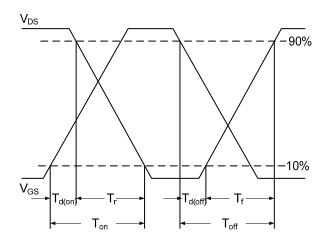


Fig.10 Switching Time Waveform

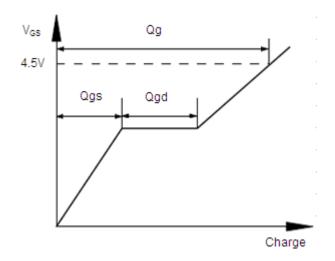


Fig.11 Gate Charge Waveform



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